

REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	2024.04.08	

A

A

B

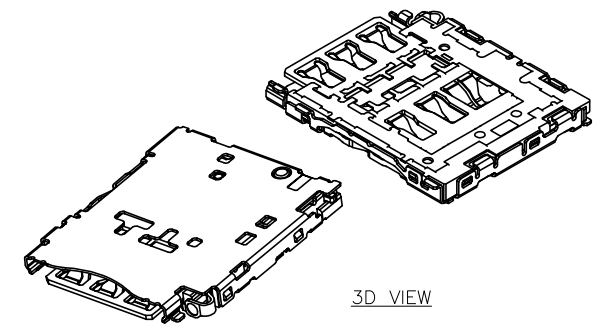
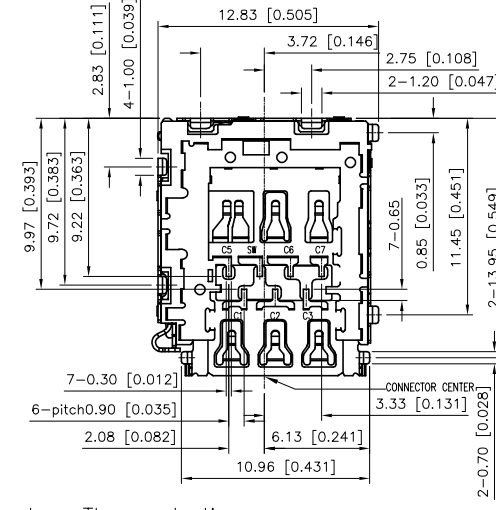
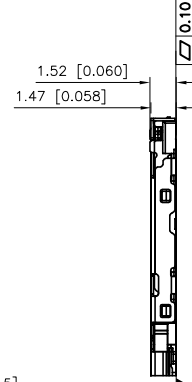
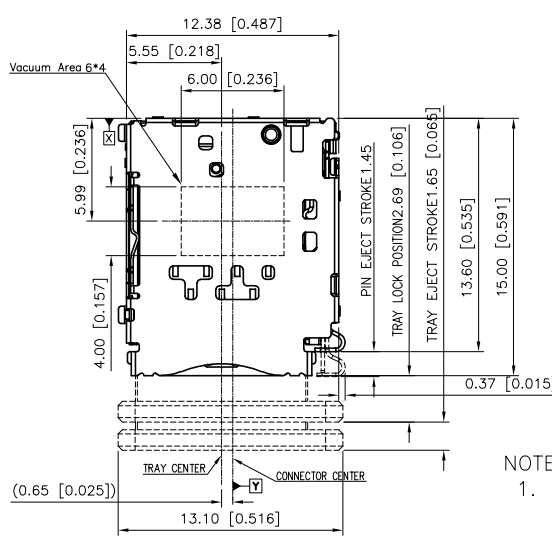
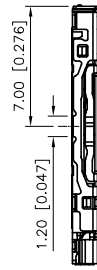
B

C

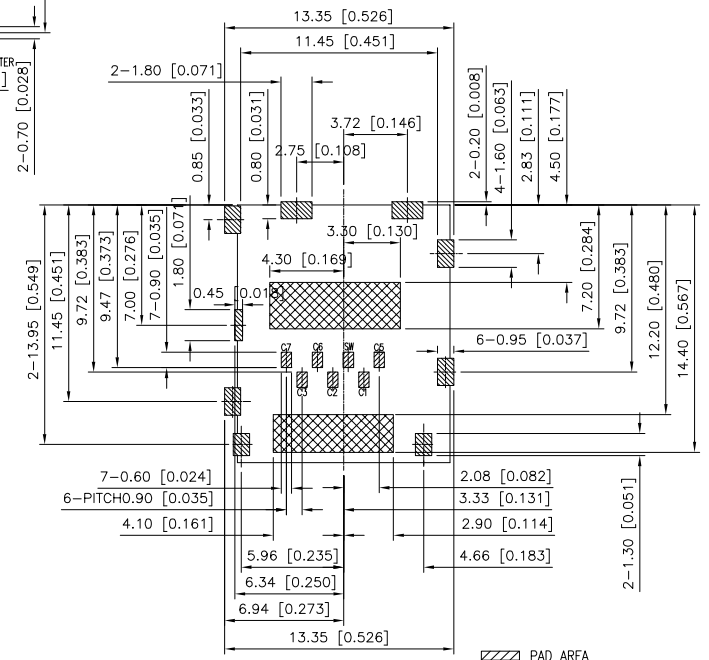
C

D

D



3D VIEW



▨ PAD AREA
▨ KEEP OUT AREA
▨ NO COPPER AREA
(NO Trace&Via&GND)
▨ GND PATTERN ONLY

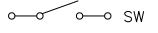
RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)

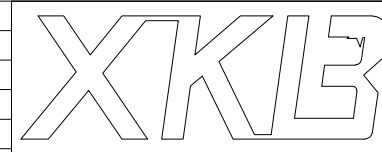
NOTE:

- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, $T=0.08 \pm 0.01$ mm)
 - 1-3 Cover: SUS304-H $T=0.15 \pm 0.03$ mm
- Plating:
 - 2-1 Contact terminal:
Contact area: Gold 1u" Min.
Solder area: Gold 0.8u" Min.
Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
Underplating: Ni overall 30u" Min.
Solder area: Gold 0.8u" Min.
- Specification:
 - 3-1. Current Rating: 0.5A max.
 - 3-2. Contact Resistance: 50 mOhms max
 - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5. Operating Temperature: -40°C to $+85^{\circ}\text{C}$
 - 3-6. Mating Cycles: 5000 Insertions

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

COMPOSITION OF DETECTION	ANGLAR	$\pm 5^{\circ}$
CARD DETECT(SW)	X.	± 0.40
C5  SW	X.x	± 0.30
CARD DETECTION/SWITCH	X.xx	± 0.20
CARD INSTALLATION: ON	X.xxx	± 0.15
NON CARD: OFF	UNSPECIFIED TOLERANCES	



XKB INDUSTRIAL PRECISION CO., LIMITED

DESIGN	桑 葚	VIEW: 	MODEL TYPE: NANO SIM H1.5 CARD
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1131-18
APPROVED		SIZE: A4	DWG NO.:
		SCALE N/A	PAGE 1/1
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